

ABSTRACT OF THE DISCLOSURE

A method for forming by molding a plastic protective package for an electronic integrated circuit that includes an electronic device activated from the outside of said protective package. The method includes: dispensing a covering layer of elastic material on a portion of said electronic device; shaping said covering layer to form a projecting portion from a surface of said electronic device; molding said electronic integrated circuit in said plastic protective package using a mold including at least a half-mold abutting against said projecting portion; and obtaining a hole or a window formed in alignment with said projecting portion in said protective package.

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